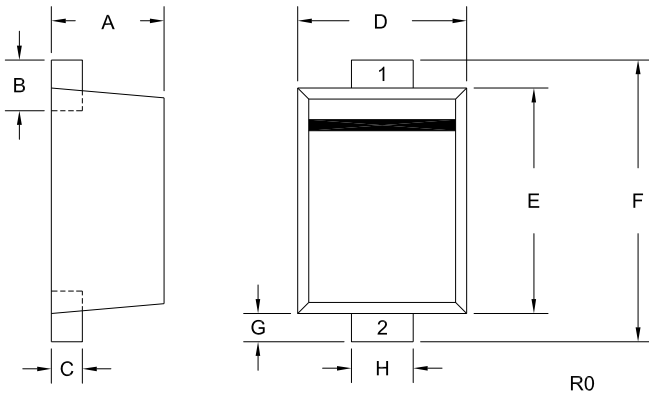


**Package Details**  
SOD-923 Case



**Mechanical Drawing**



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.015	0.016	0.39	0.41
B	0.004	0.010	0.10	0.26
C	0.003	0.006	0.08	0.14
D	0.022	0.026	0.55	0.65
E	0.030	0.033	0.75	0.85
F	0.035	0.043	0.90	1.10
G	0.002	0.006	0.05	0.15
H	0.007	0.011	0.17	0.27

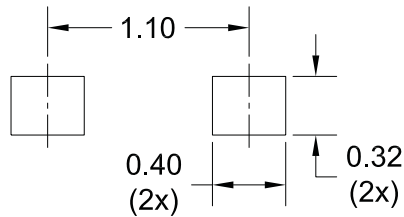
SOD-923 (REV: R0)

**Lead Code:**

- 1) Cathode
- 2) Anode

**Part Marking:** 2-3 Character Alpha/Numeric Code

**Mounting Pad Geometry** (Dimensions in mm)



R0

R1 (4-March 2010)

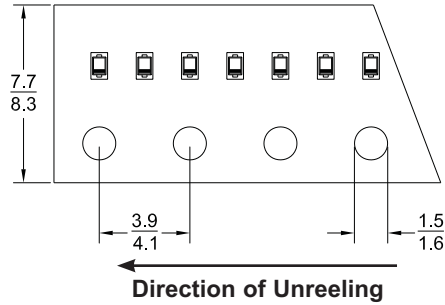
# Package Details

## SOD-923 Case



### Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



\* Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

### Packaging Base

7" Reel = 8,000 pcs.

### Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

### Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	9	72,000	9x9x5	23x23x13	3	2
	18	144,000	9x9x9	23x23x23	6	3
	40	320,000	21x9x9	53x23x23	13	6
	108	864,000	27x9x17	69x23x43	34	16

### Ordering Information

- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R1 (4-March 2010)

# Material Composition Specification

SOD-923 Case

Pb (lead)-free plating



Device average mass . . . . . 0.5 mg

Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	7.5%	0.037	Si	7440-21-3	7.5%	0.0375	74,970
bond wire	gold	0.76%	0.004	Au	7440-57-5	0.76%	0.0038	7,597
leadframe	copper w/ silver plating	47.14%	0.236	Cu	7440-50-8	45.98%	0.23	459,816
				Ag	7440-22-4	1.16%	0.0058	11,595
encapsulation*	EMC	42.14%	0.211	silica	7631-86-9	30.39%	0.152	303,878
				epoxy resin	Proprietary	10.6%	0.053	105,958
				Sb <sub>2</sub> O <sub>3</sub>	1309-64-4	0.84%	0.0042	8,397
				TBBA	79-94-7	0.22%	0.0011	2,199
				carbon	1333-86-4	0.1%	0.0005	1,000
	EMC GREEN	42.14%	0.211	silica	60676-86-0	28.17%	0.141	281,682
				epoxy resin	29690-82-2	6.4%	0.032	63,979
				phenol resin	9003-35-4	3.21%	0.016	32,099
				carbon black	1333-86-4	0.22%	0.001	2,184
				metal hydroxide	1309-42-8	4.15%	0.021	41,488
plating	100% matte tin	2.46%	0.012	Sn	7440-31-5	2.46%	0.0123	24,590

\*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (9-March 2010)